

**N-Channel MOSFET** 

#### **General Description**

The WSR4086 is the highest performance trench N-Channel MOSFET with extreme high cell density, which provide excellent RDSON and gate chargefor most of the device is suitable for use as a Battery protection or in other Switching application.

The WSR4086 meet the RoHS and GreenProduct requirement 100% EAS guaranteed withfull function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

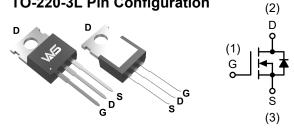
#### **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
40V	5.5mΩ	86A

#### **Applications**

- Battery protection
- Load switch
- Uninterruptible power supply

#### **TO-220-3L Pin Configuration**



#### **Absolute Maximum Ratings**

Symbol	Parameter Rating		Units
V <sub>DS</sub>	Drain-Source Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	86	A
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	41	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup> , T <sub>C</sub> =25°C 240		A
EAS	Avalanche Energy, Single pulse,L=0.5mH	100	mJ
I <sub>AS</sub>	Avalanche Current, Single pulse,L=0.5mH	20	A
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup>	46	W
T <sub>STG</sub>	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range	°C	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		2.7	°C/W



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### Electrical Characteristics (TJ=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V	
$\triangle BV_{DSS} / \triangle T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to $25^{\circ}$ C , I <sub>D</sub> =1mA		0.034		V/℃	
	2	V <sub>GS</sub> =10V,I <sub>D</sub> =30A		5.5	7.0		
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V,I <sub>D</sub> =20A		9.0	12	mΩ	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_{D}=250 \text{uA}$	1.0	1.5	2.5	V	
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}40V$ , $V_{\text{GS}}\text{=}0V$ , $T_{\text{J}}\text{=}25^\circ\!\mathbb{C}$			1	uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA	
Qg	Total Gate Charge (10V)			37			
Q <sub>gs</sub>	Gate-Source Charge	$V_{\text{DS}}\text{=}20V$ , $V_{\text{GS}}\text{=}10V$ , $I_{\text{D}}\text{=}30A$		6		nC	
Q <sub>gd</sub>	Gate-Drain Charge			7			
T <sub>d(on)</sub>	Turn-On Delay Time			12			
Tr	Rise Time	$V_{\text{DD}}\text{=}20V,I_{\text{D}}\text{=}30A$ , RL=10 ,		12		ns	
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G$ =3 $\Omega$ , $V_{GS}$ =10V		9		115	
T <sub>f</sub>	Fall Time			38			
C <sub>iss</sub>	Input Capacitance			2400			
C <sub>oss</sub>	Output Capacitance	$V_{DS}$ =20V , $V_{GS}$ =0V , f=1MHz		192		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			165			

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current				60	А
I <sub>SM</sub>	Pulsed Source Current	$V_G = V_D = 0V$ , Force Current			240	А
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =30A , TJ=25℃			1.2	V
t <sub>rr</sub>	Reverse Recovery Time			22		nS
Q <sub>rr</sub>	Reverse Recovery Charge	IF=20A,dI/dt=100A/µs,Tյ=25℃		11		nC

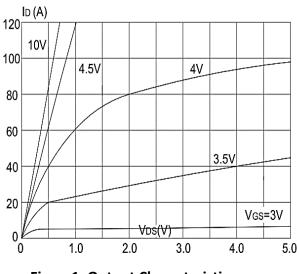
Note :

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.5mH,I<sub>AS</sub>=20A
- 4. The power dissipation is limited by 150  $^\circ\!\!\mathbb{C}$  junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



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### **Typical Characteristics**





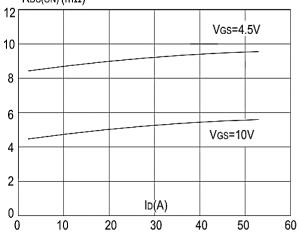
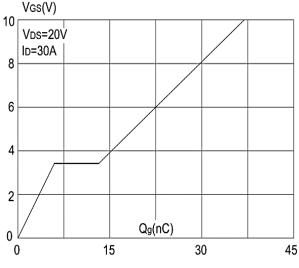
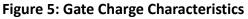
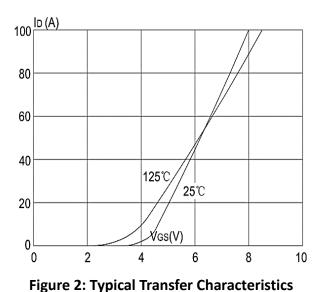
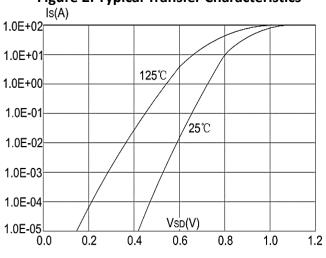


Figure 3:On-resistance vs. Drain Current

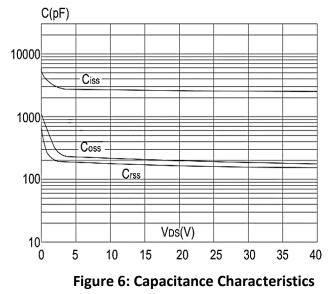






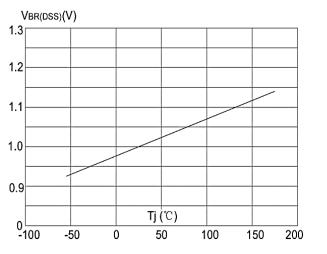


**Figure 4: Body Diode Characteristics** 





#### **N-Channel MOSFET**





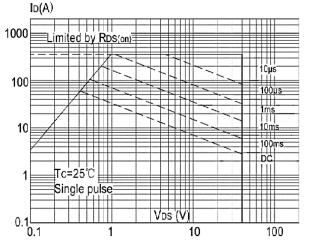
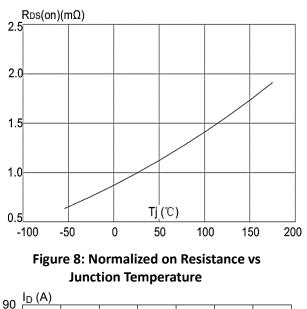


Figure 9: Maximum Safe Operating Area



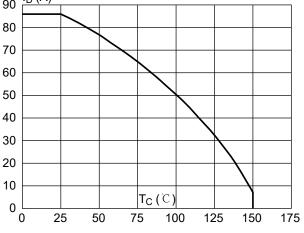
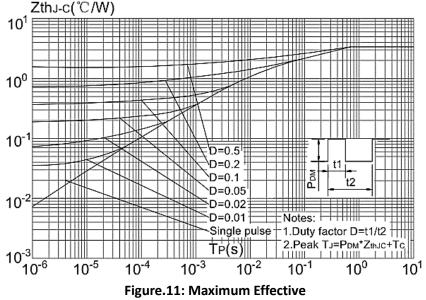


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

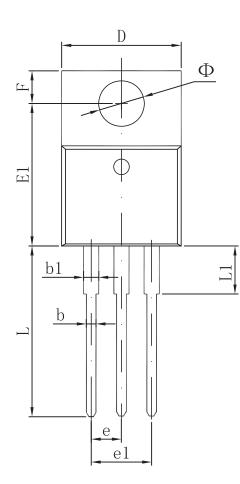


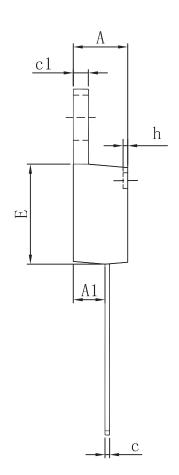




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## Packaging information





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Мах	Min	Max	
А	4.470	4.670	0.176	0.184	
A1	2.520	2.820	0.099	0.111	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
Е	8.500	8.900	0.335	0.350	
E1	12.060	12.460	0.475	0.491	
е	2.540	) TYP	0.100	) TYP	
e1	4.980	5.180	0.196	0.204	
F	2.590	2.890	0.102	0.114	
h	0.000	0.300	0.000	0.012	
L	13.400	13.800	0.528	0.543	
L1	3.560	3.960	0.140	0.156	
Ф	3.735	3.935	0.147	0.155	



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